



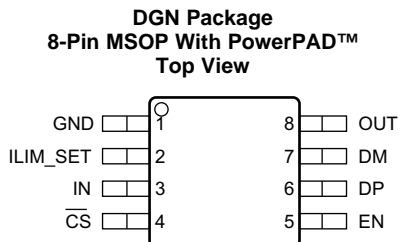
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## 4 Revision History

Changes from Original (June 2012) to Revision A	Page
<ul style="list-style-type: none"> <li>Added <i>ESD Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i>, <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....</li> </ul>	<b>1</b>
<ul style="list-style-type: none"> <li>Deleted <i>Ordering Information</i> table, see POA at the end of the document.....</li> </ul>	<b>1</b>

## 5 Pin Configuration and Functions



### Pin Functions

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NAME	NO.		
$\overline{CS}$	4	O	Active-low, open-drain output. When OUT current is more than approximately half of the current limit set by a resistor on ILIM_SET pin, the output is active low. Maximum sink current is 10 mA.
DM	7	I/O	Connected to the D– or D+ line of USB connector. Provide the correct voltage with an attached portable equipment for DCP detection, high impedance while disabled.
DP	6	I/O	Connected to the D+ or D– line of USB connector. Provide the correct voltage with an attached portable equipment for DCP detection, high impedance while disabled.
EN	5	I	Logic-level control input. When it is high, turns power switch on, when it is low, turns power switch off and turns DP and DM into the high impedance state.
GND	1	G	Ground connection.
ILIM_SET	2	I	External resistor used to set current limiting Threshold. TI recommends $16.9\text{ k}\Omega \leq R_{ILIM\_SET} \leq 750\text{ k}\Omega$ .
IN	3	P	Power supply input voltage connected to the power switch. Connect a ceramic capacitor with a value of 0.1- $\mu$ F or greater from the IN pin to GND as close to the device as possible.
OUT	8	O	Power-switch output. Connect to VBUS of USB
PowerPAD	PowerPAD	G	Ground connection.

(1) G = Ground, I = Input, O = Output, P = Power

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT
Voltage	IN	Supply voltage	−0.3	7	V
	EN, ILIM_SET	Input voltage	−0.3	7	
	OUT, $\overline{\text{CS}}$		−0.3	7	
	IN to OUT		−7	7	
	DP output voltage	DM output	−0.3	IN+0.3 or 5.7	
	DP input voltage	DM input	−0.3	IN+0.3 or 5.7	
Current	DP input current, DM input current	Continuous output sink current	35		mA
	DP output current, DM output current	Continuous output source current	35		
	$\overline{\text{CS}}$	Continuous output sink current	10		
	ILIM_SET	Continuous output source current	Internally limited		
Temperature	Operating junction temperature, T <sub>J</sub>		Internally limited		
	Storage temperature, T <sub>stg</sub>		−65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 6.2 ESD Ratings

			VALUE	UNIT
$V_{\text{(ESD)}}$ Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	All pins except 6 and 7	±2000	V
		Pins 6 and 7	±7500	
	Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>		±500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

voltages are referenced to GND (unless otherwise noted), positive current are into pins.

		MIN	MAX	UNIT
$V_{\text{IN}}$	Input voltage of IN	4.5	5.5	V
$V_{\overline{\text{CS}}}$	Input voltage of $\overline{\text{CS}}$	0	5.5	
$V_{\text{EN}}$	Input voltage of EN	0	5.5	
$V_{\text{DP}}$	DP data line input voltage	0	5.5	
$V_{\text{DM}}$	DM data line input voltage	0	5.5	
$I_{\text{DP}}$	Continuous sink/source current		±10	mA
$I_{\text{DM}}$	Continuous sink/source current		±10	
$I_{\overline{\text{CS}}}$	Continuous sink current		2	
$I_{\text{OUT}}$	Continuous output current of OUT		2.2	A
$R_{\text{ILIM\_SET}}$	A resistor of current limit, ILIM_SET to GND	16.9	750	kΩ
$T_J$	Operating junction temperature	−40	125	°C

## 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TPS2511	UNIT
		DGN (MSOP-PowerPAD)	
		8 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	65.2	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	53.3	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	36.9	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	3.9	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	36.6	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	13.4	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.5 Electrical Characteristics

Conditions are  $-40^{\circ}\text{C} \leq (T_J = T_A) \leq 125^{\circ}\text{C}$ ,  $4.5\text{ V} \leq V_{IN} \leq 5.5\text{ V}$ ,  $V_{EN} = V_{IN}$  and  $R_{ILIM\_SET} = 22.1\text{ k}\Omega$ . Positive current are into pins. Typical values are at  $25^{\circ}\text{C}$ . All voltages are with respect to GND (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SWITCH						
R <sub>DS(on)</sub>	Static drain-source ON-state resistance	I <sub>OUT</sub> = 2 A		70	120	mΩ
		I <sub>OUT</sub> = 2 A, −40°C ≤ (T <sub>J</sub> = T <sub>A</sub> ) ≤ 85°C		70	105	
		I <sub>OUT</sub> = 2 A, T <sub>J</sub> = T <sub>A</sub> = 25°C		70	84	
I <sub>REV</sub>	Reverse leakage current	V <sub>OUT</sub> = 5.5 V, V <sub>IN</sub> = V <sub>EN</sub> = 0 V		0.01	2	μA
DISCHARGE						
R <sub>DCHG</sub>	Discharge resistance	V <sub>OUT</sub> = 4 V	400	500	630	Ω
CURRENT LIMIT						
I <sub>OS</sub>	OUT short-circuit current limit	R <sub>ILIM_SET</sub> = 44.2 kΩ	1060	1160	1270	mA
		R <sub>ILIM_SET</sub> = 22.1 kΩ	2110	2300	2550	
		R <sub>ILIM_SET</sub> = 16.9 kΩ	2760	3025	3330	
HICCUP MODE						
V <sub>OUT_SHORT</sub>	OUT voltage threshold of going into hiccup mode	V <sub>IN</sub> = 5 V, R <sub>ILIM_SET</sub> = 210 kΩ	3.6	3.8	4.1	V
UNDERVOLTAGE LOCKOUT						
V <sub>UVLO</sub>	IN UVLO threshold voltage, rising		3.9	4.1	4.3	V
	Hysteresis <sup>(1)</sup>			100		mV
SUPPLY CURRENT						
I <sub>IN_OFF</sub>	Disabled, IN supply current	V <sub>EN</sub> = 0 V, V <sub>IN</sub> = 5.5 V, −40°C ≤ T <sub>J</sub> ≤ 85°C		0.1	2	μA
I <sub>IN_ON</sub>	Enabled, IN supply current	V <sub>EN</sub> = V <sub>IN</sub> , R <sub>ILIM_SET</sub> = 210 kΩ		180	230	
THERMAL SHUTDOWN						
	Temperature rising threshold <sup>(1)</sup>	Not in current limit	155			°C
		In current limit	135			
	Hysteresis <sup>(1)</sup>			10		
OUT CURRENT DETECTION						
I <sub>HCC_TH</sub>	Load detection current threshold, rising <sup>(1)</sup>	R <sub>ILIM_SET</sub> = 22.1 kΩ		1060		mA
		R <sub>ILIM_SET</sub> = 44.2 kΩ		560		
I <sub>HCC_TH_HYS</sub>	Load detection current Hysteresis <sup>(1)</sup>	R <sub>ILIM_SET</sub> = 22.1 kΩ		230		mA
		R <sub>ILIM_SET</sub> = 44.2 kΩ		120		
V <sub>CS</sub>	CS output active-low voltage <sup>(1)</sup>	I <sub>CS</sub> = 1 mA	0	80	140	mV

(1) Specified by design. Not production tested.

## Electrical Characteristics (continued)

Conditions are  $-40^{\circ}\text{C} \leq (T_J = T_A) \leq 125^{\circ}\text{C}$ ,  $4.5\text{ V} \leq V_{IN} \leq 5.5\text{ V}$ ,  $V_{EN} = V_{IN}$  and  $R_{ILIM\_SET} = 22.1\text{ k}\Omega$ . Positive current are into pins. Typical values are at  $25^{\circ}\text{C}$ . All voltages are with respect to GND (unless otherwise noted).

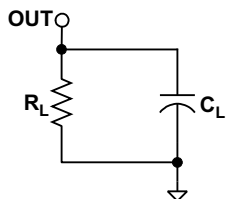
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
ENABLE INPUT (EN)						
V <sub>EN_TRIP</sub>	EN threshold voltage, falling		0.9	1.1	1.65	V
V <sub>EN_TRIP_HYS</sub>	Hysteresis		100	200	300	mV
I <sub>EN</sub>	Leakage current	V <sub>EN</sub> = 0 V or V <sub>EN</sub> = 5.5 V	−0.5		0.5	μA
BC 1.2 DCP MODE (SHORT MODE)						
R <sub>DPM_SHORT</sub>	DP and DM shorting resistance	V <sub>DP</sub> = 0.8 V, I <sub>DM</sub> = 1 mA		125	200	Ω
R <sub>DCHG_SHORT</sub>	Resistance between DP/DM and GND	V <sub>DP</sub> = 0.8 V	400	700	1300	kΩ
V <sub>DPL_TH_DETACH</sub>	Voltage threshold on DP under which the device goes back to divider mode		310	330	350	mV
V <sub>DPL_TH_DETACH_HYS</sub>	Hysteresis			50 <sup>(1)</sup>		mV
DIVIDER MODE						
V <sub>DP_2.7V</sub>	DP output voltage	V <sub>IN</sub> = 5 V	2.57	2.7	2.84	V
V <sub>DM_2.0V</sub>	DM output voltage	V <sub>IN</sub> = 5 V	1.9	2	2.1	
R <sub>DP_PAD1</sub>	DP output impedance	I <sub>DP</sub> = −5 μA	24	30	40	kΩ
R <sub>DM_PAD1</sub>	DM output impedance	I <sub>DM</sub> = −5 μA	24	30	40	
1.2 V / 1.2 V MODE						
V <sub>DP_1.2V</sub>	DP output voltage	V <sub>IN</sub> = 5 V	1.12	1.2	1.28	V
V <sub>DM_1.2V</sub>	DM output voltage	V <sub>IN</sub> = 5 V	1.12	1.2	1.28	V
R <sub>DP_PAD2</sub>	DP output impedance	I <sub>DP</sub> = −5 uA	80	105	130	kΩ
R <sub>DM_PAD2</sub>	DM output impedance	I <sub>DM</sub> = −5 uA	80	105	130	kΩ

## 6.6 Switching Characteristics

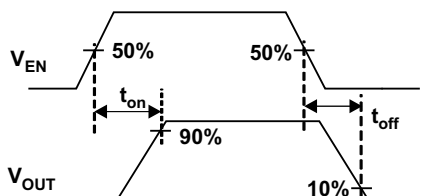
Conditions are  $-40^{\circ}\text{C} \leq (T_J = T_A) \leq 125^{\circ}\text{C}$ ,  $4.5\text{ V} \leq V_{IN} \leq 5.5\text{ V}$ ,  $V_{EN} = V_{IN}$  and  $R_{ILIM\_SET} = 22.1\text{ k}\Omega$ . Positive current are into pins. Typical values are at  $25^{\circ}\text{C}$ . All voltages are with respect to GND (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SWITCH						
t <sub>r</sub>	OUT voltage rise time	C <sub>L</sub> = 1 μF, R <sub>L</sub> = 100 Ω, V <sub>IN</sub> = 5 V see <a href="#">Figure 1</a> , <a href="#">Figure 3</a>		1	1.5	ms
t <sub>f</sub>	OUT voltage fall time	C <sub>L</sub> = 1 μF, R <sub>L</sub> = 100 Ω, V <sub>IN</sub> = 5 V see <a href="#">Figure 1</a> , <a href="#">Figure 3</a>	0.2	0.35	0.5	
CURRENT LIMIT						
t <sub>IOS</sub>	Short circuit response time <sup>(1)</sup>	V <sub>IN</sub> = 5 V, R <sub>L</sub> = 50 mΩ, 2 inches lead length, See <a href="#">Figure 4</a>		1.5		μs
HICCUP MODE						
t <sub>OS_DEG</sub>	ON-time of hiccup mode <sup>(1)</sup>	V <sub>IN</sub> = 5 V, R <sub>L</sub> = 0		16		ms
t <sub>SC_TURN_OFF</sub>	OFF-time of hiccup mode <sup>(1)</sup>	V <sub>IN</sub> = 5 V, R <sub>L</sub> = 0		12		s
OUT CURRENT DETECTION						
t <sub>CS_EN</sub>	$\overline{\text{CS}}$ deglitch time during turning on <sup>(1)</sup>	I <sub>CS</sub> = 1 mA		8		ms
ENABLE INPUT (EN)						
t <sub>on</sub>	OUT voltage turnon time	C <sub>L</sub> = 1 μF, R <sub>L</sub> = 100 Ω, see <a href="#">Figure 1</a> , <a href="#">Figure 2</a>		2.6	5	ms
t <sub>off</sub>	OUT voltage turnoff time			1.7	3	

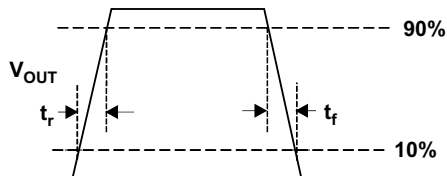
(1) Specified by design. Not production tested.



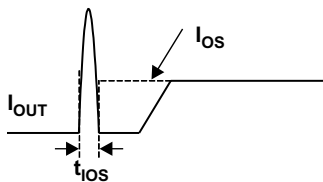
**Figure 1. Output Rise and Fall Test Load**



**Figure 2. Enable Timing, Active High Enable**



**Figure 3. Power On and Power Off**



**Figure 4. Output Short-Circuit Parameters**

## 6.7 Typical Characteristics

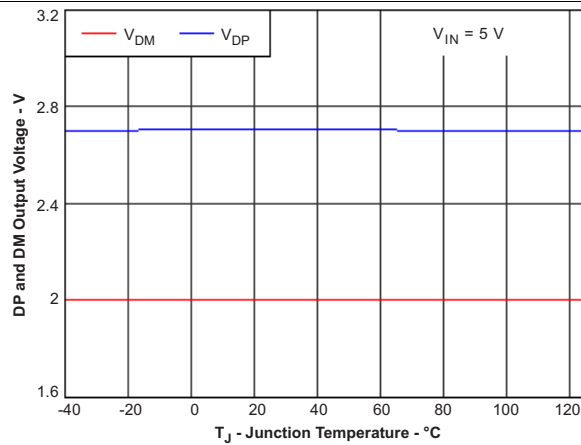


Figure 5. DP and DM Output Voltage vs Temperature

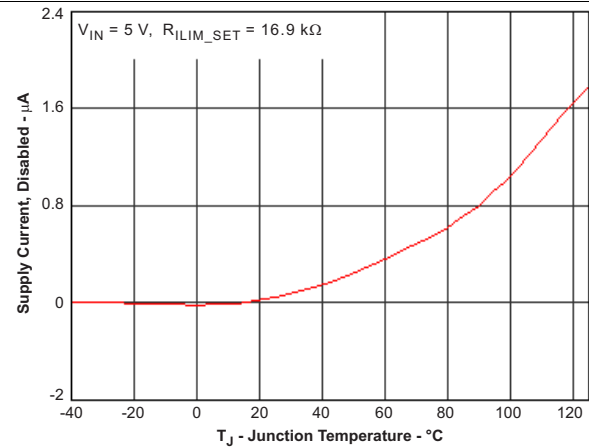


Figure 6. Supply Current Disabled vs Temperature

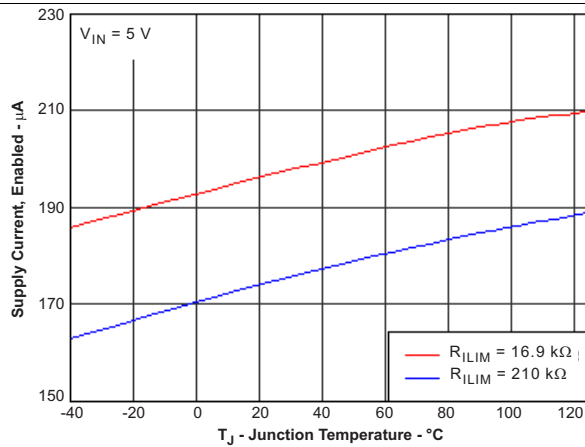


Figure 7. Supply Current Enabled vs Temperature

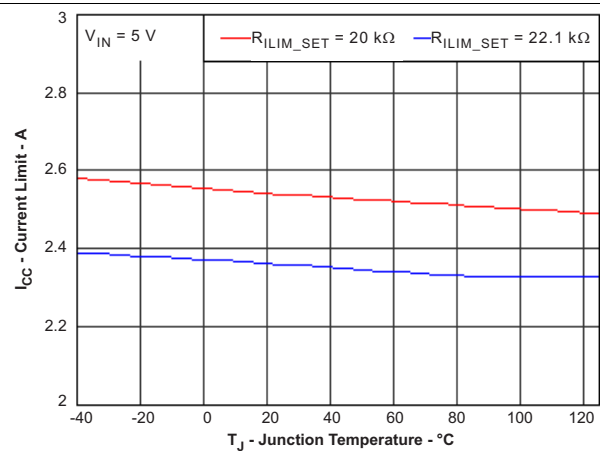


Figure 8. Current Limit vs Temperature

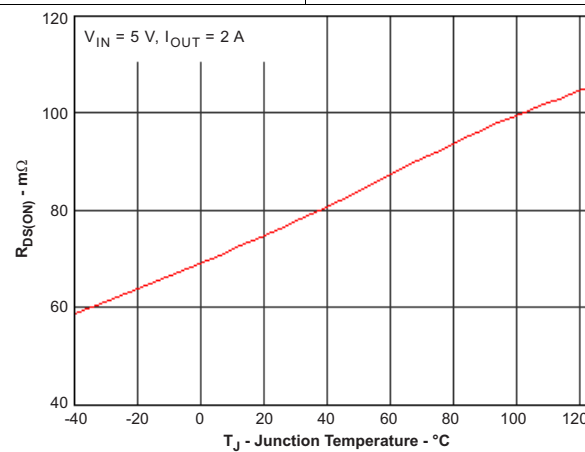


Figure 9. Power Switch ON-Resistance (R<sub>DS(ON)</sub>) vs Temperature



## 7 Detailed Description

### 7.1 Overview

The following overview references various industry standards. TI always recommends consulting the latest standard to ensure the most recent and accurate information.

Rechargeable portable equipment requires an external power source to charge its batteries. USB ports are convenient locations for charging because of an available 5-V power source. Universally accepted standards are required to ensure host and client-side devices meet the power management requirements. Traditionally, USB host ports following the USB 2.0 Specification must provide at least 500 mA to downstream client-side devices. Because multiple USB devices can be attached to a single USB port through a bus-powered hub, it is the responsibility of the client-side device to negotiate the power allotment from the host to ensure the total current draw does not exceed 500 mA. The TPS2511 provides 100 mA of current to each USB device. Each USB device can subsequently request more current, which is granted in steps of 100 mA up 500 mA total. The host may grant or deny the request based on the available current.

Additionally, the success of the USB technology makes the micro-USB connector a popular choice for wall adapter cables. This allows a portable device to charge from both a wall adapter and USB port with only one connector.

One common difficulty has resulted from this. As USB charging has gained popularity, the 500-mA minimum defined by the USB 2.0 Specification or 900 mA defined in the USB 3.0 Specification, has become insufficient for many handsets, tablets, and personal media players (PMP), which have a higher-rated charging current. Wall adapters and car chargers can provide much more current than 500 mA or 900 mA to fast charge portable devices. Several new standards have been introduced defining protocol handshaking methods that allow host and client devices to acknowledge and draw additional current beyond the 500 mA (defined in the USB 2.0 Specification) or 900 mA (defined in the USB 3.0 Specification) minimum while using a single micro-USB input connector.

The TPS2511 supports three of the most common protocols:

- USB Battery Charging Specification, Revision 1.2 (BC1.2)
- Chinese Telecommunications Industry Standard YD/T 1591-2009
- Divider Mode

In these protocols there are three types of charging ports defined to provide different charging current to client-side devices. These charging ports are defined as:

- Standard downstream port (SDP)
- Charging downstream port (CDP)
- Dedicated charging port (DCP)

The BC1.2 Specification defines a charging port as a downstream facing USB port that provides power for charging portable equipment.

[Table 1](#) lists different port operating modes according to the BC1.2 Specification.

**Table 1. Operating Modes Table**

PORT TYPE	SUPPORTS USB 2.0 COMMUNICATION	MAXIMUM ALLOWABLE CURRENT DRAWN BY PORTABLE EQUIPMENT (A)
SDP (USB 2.0)	Yes	0.5
SDP (USB 3.0)	Yes	0.9
CDP	Yes	1.5
DCP	No	1.5

The BC1.2 Specification defines the protocol necessary to allow portable equipment to determine what type of port it is connected to so that it can allot its maximum allowable current drawn. The hand-shaking process is two steps. During step one, the primary detection, the portable equipment outputs a nominal 0.6-V output on its D+ line and reads the voltage input on its D– line. The portable device concludes it is connected to a SDP if the voltage is less than the nominal data detect voltage of 0.3 V. The portable device concludes that it is connected to a Charging Port if the D– voltage is greater than the nominal data detect voltage of 0.3 V and less than 0.8 V.

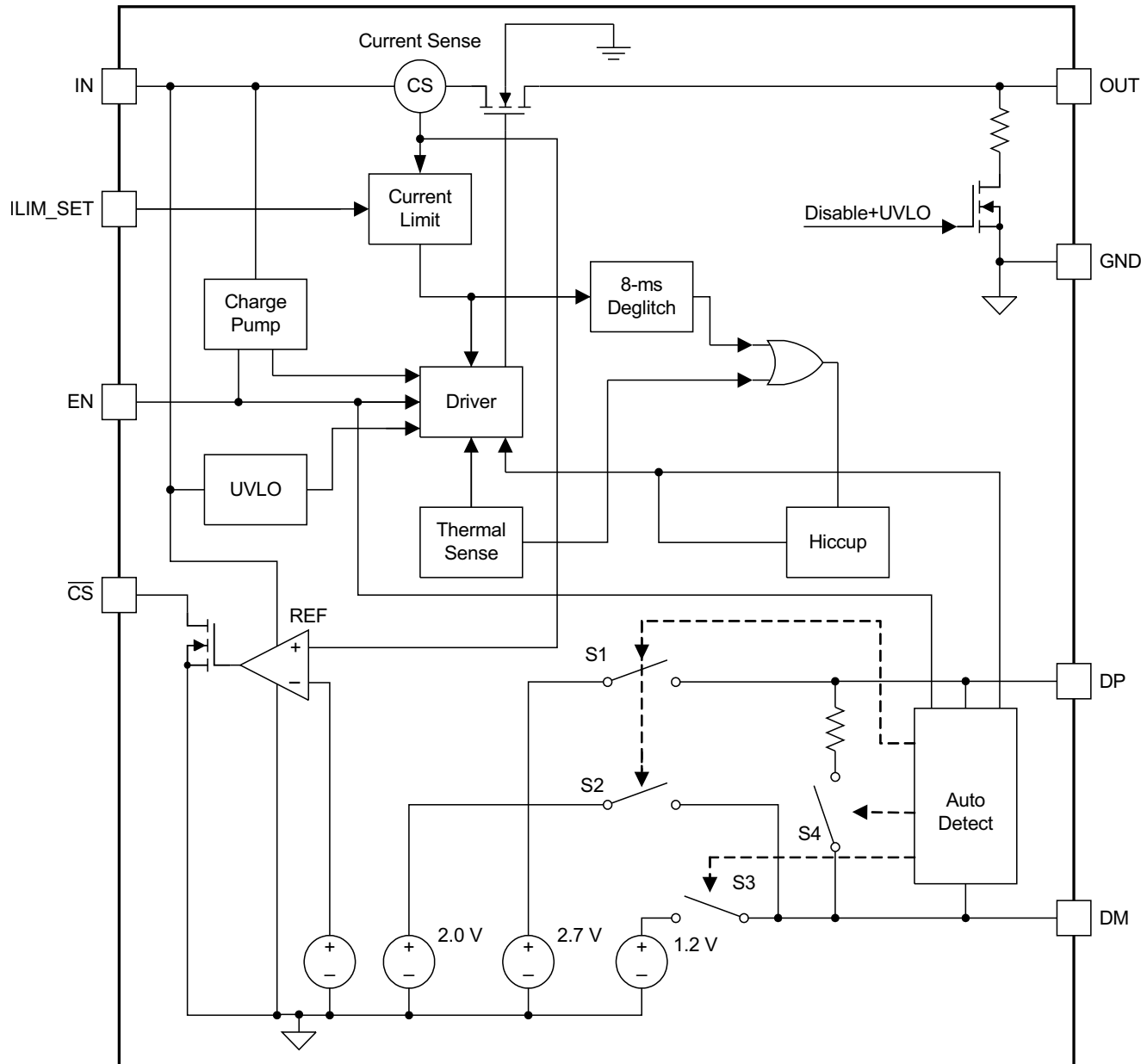
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The second step, the secondary detection, is necessary for portable equipment to determine between a CDP and a DCP. The portable device outputs a nominal 0.6-V output on its D<sup>−</sup> line and reads the voltage input on its D<sup>+</sup> line. The portable device concludes it is connected to a CDP if the data line being remains is less than the nominal data detect voltage of 0.3 V. The portable device concludes it is connected to a DCP if the data line being read is greater than the nominal data detect voltage of 0.3 V and less than 0.8 V.

### 7.2 Functional Block Diagram

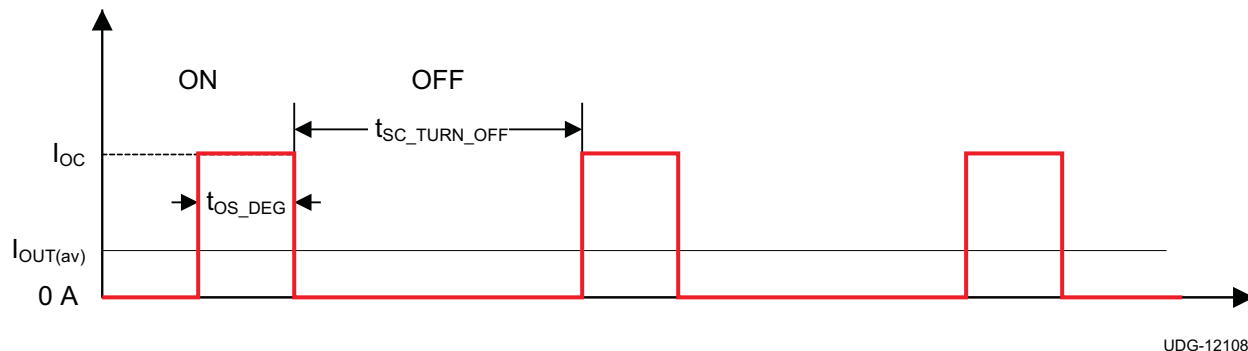


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## 7.3 Feature Description

### 7.3.1 Overcurrent Protection

During an overload condition, the TPS2511 maintains a constant output current and reduces the output voltage accordingly. If the output voltage falls to less than 3.8 V for 16 ms, the TPS2511 turns off the output for a period of 12 seconds as shown in Figure 10. This operation is referred to as hiccup mode. The device stays in hiccup mode (power cycling) until the overload condition is removed. Therefore the average output current is significantly reduced to greatly improve the thermal stress of the device while the OUT pin is shorted.



**Figure 10. OUT Pin Short-Circuit Current in Hiccup Mode**

Two possible overload conditions can occur. In the first condition, the output has been shorted before the device is enabled or before the voltage of IN has been applied. The TPS2511 senses the short and immediately switches into hiccup mode of constant-current limiting. In the second condition, a short or an overload occurs while the device is enabled. At the instant the overload occurs, high currents may flow for several microseconds before the current limit circuit can react. The device operates in constant-current mode for a period of 16 ms after the current limit circuit has responded, then switches into hiccup mode (power cycling).

## Feature Description (continued)

### 7.3.2 Current Limit Threshold

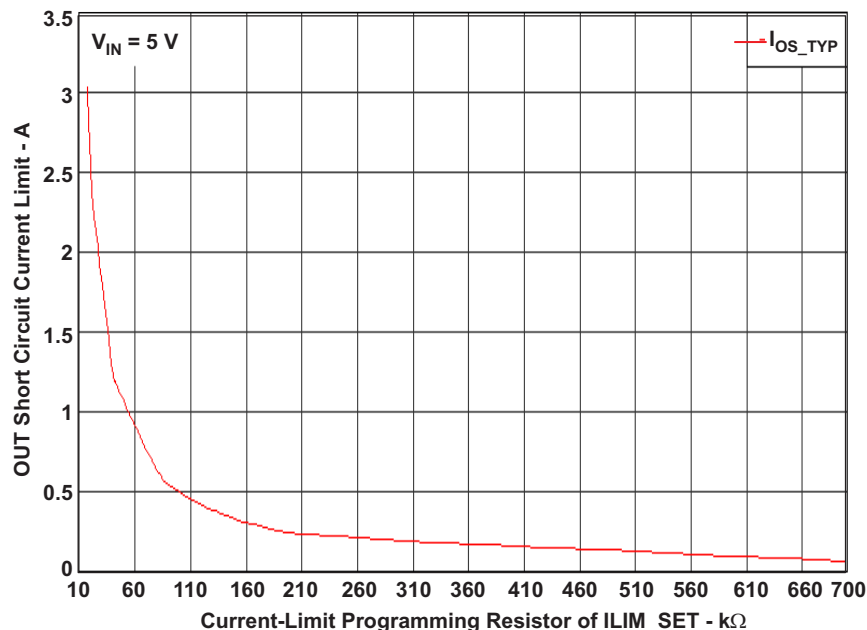
The TPS2511 has a current limiting threshold that is externally programmed with a resistor. Equation 1 and Figure 11 help determine the typical current limit threshold.

$$I_{OS\_TYP} = \frac{51228}{R_{ILIM}}$$

where

- $I_{OS\_TYP}$  is in mA and  $R_{ILIM}$  is in  $k\Omega$
- $I_{OS\_TYP}$  has a better accuracy if  $R_{ILIM}$  is less than 210  $k\Omega$

(1)



**Figure 11. Typical Current Limit vs Programming Resistor**

### 7.3.3 Current-Sensing Report ( $\overline{CS}$ )

The  $\overline{CS}$  open-drain output is asserted immediately when the OUT pin current is more than about half of the current limit set by a resistor on ILIM\_SET pin. Built-in hysteresis improves the ability to resist current noise on the OUT pin. The  $\overline{CS}$  output is active low. The recommended operating sink current is less than 2 mA and maximum sink current is 10 mA.

### 7.3.4 Undervoltage Lockout (UVLO) and Enable (EN)

The undervoltage lockout (UVLO) circuit disables the power switch and other functional circuits until the input voltage reaches the UVLO turnon threshold. Built-in hysteresis prevents unwanted oscillations on the output due to input voltage drop from large current surges.

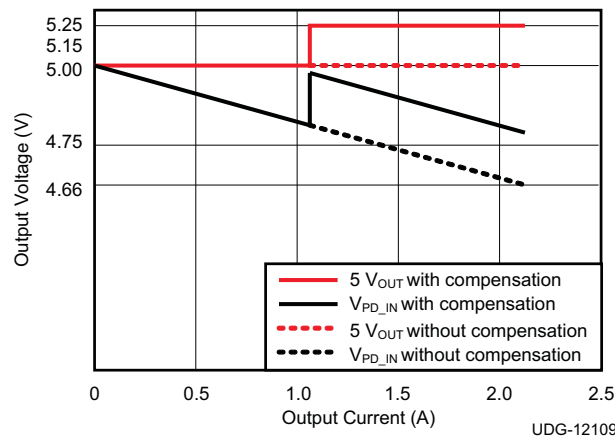
The logic input of the EN pin disables all of the internal circuitry while maintaining the power switch off. A logic-high input on the EN pin enables the driver, control circuits, and power switch. The EN input voltage is compatible with both TTL and CMOS logic levels.

### 7.3.5 Soft Start, Reverse Blocking, and Discharge Output

The power MOSFET driver incorporates circuitry that controls the rise and fall times of the output voltage to limit large current and voltage surges on the input supply, and provides built-in soft-start functionality. The TPS2511 power switch blocks current from the OUT pin to the IN pin when turned off by the UVLO or disabled. The TPS2511 includes an output discharge function. A 500- $\Omega$  (typical) discharge resistor dissipates stored charge and leakage current on the OUT pin when the device is in UVLO or disabled. However as this circuit is biased from the IN pin, the output discharge is not active when the input approaches 0 V.

### 7.3.6 Thermal Sense

## Feature Description (continued)



**Figure 13. TPS2511  $\overline{CS}$  Function**

Equation 2 through Equation 5 refer to Figure 12.

The power supply output voltage is calculated in Equation 2.

$$5V_{OUT} = \frac{(R_1 + R_2 + R_3) \times V_{FB}}{R_3} \quad (2)$$

$5V_{OUT}$  and  $V_{FB}$  are known. If  $R_3$  is given and  $R_1$  is fixed,  $R_2$  can be calculated. The  $5V_{OUT}$  voltage change with compensation is shown in Equation 3 and Equation 4.

$$\Delta V = \frac{(R_2 + R_3) \times R_1 \times V_{FB}}{R_3 \times R_4} \quad (3)$$

$$\Delta V = \left( \frac{5V_{OUT}}{V_{FB}} - \frac{R_1}{R_3} \right) \frac{R_1 \times V_{FB}}{R_4} \quad (4)$$

If  $R_1$  is less than  $R_3$ , then Equation 4 can be simplified as Equation 5.

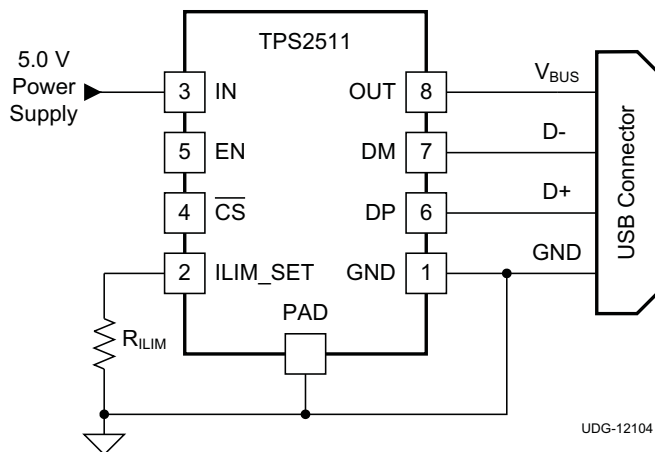
$$\Delta V \approx \frac{5V_{OUT} \times R_1}{R_4} \quad (5)$$

### 7.3.8 Divide Mode Selection of 5-W and 10-W USB Chargers

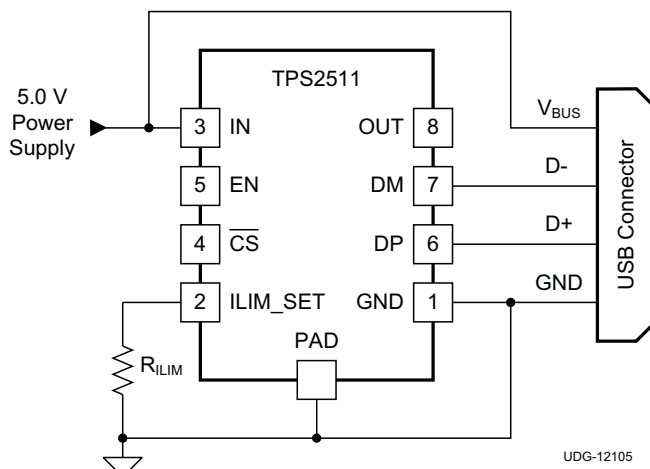
The TPS2511 provides two types of connections between the DP pin and the DM pin and between the D+ data line and the D– data line of the USB connector for a 5-W USB charger and a 10-W USB charger with a single USB port. For a 5-W USB charger, the DP pin is connected to the D– line and the DM pin is connected to the D+ line. This is shown in Figure 16 and Figure 17. It is necessary to apply DP and DM to D+ and D– of USB connector for 10-W USB chargers. See Figure 14 and Figure 15. Table 2 shows different charging schemes for both 5-W and 10-W USB charger solutions

**Table 2. Charging Schemes for 5-W and 10-W USB Chargers**

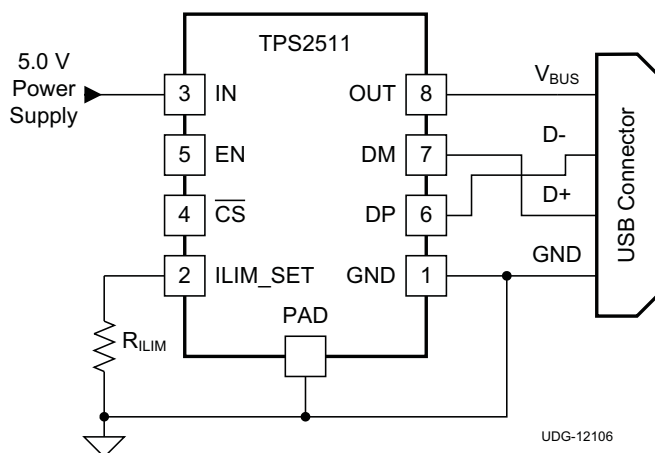
USB CHARGER TYPE	CONTAINING CHARGING SCHEMES		
5-W	Divider1	1.2 V on both D+ and D– Lines	BC1.2 DCP
10-W	Divider2	1.2 V on both D+ and D– Lines	BC1.2 DCP



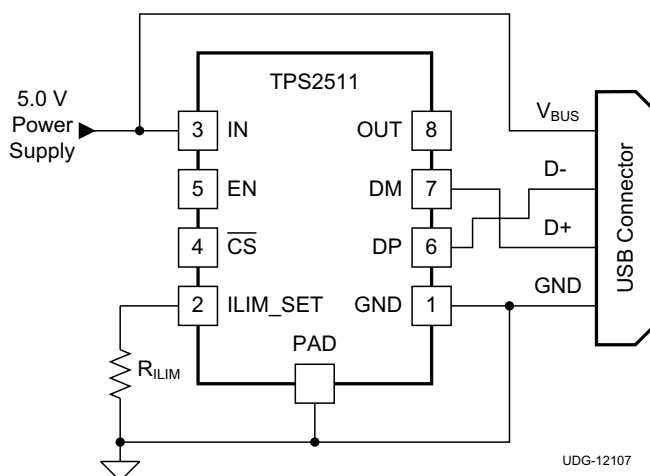
**Figure 14. 10-W USB Charger Application With Power Switch**



**Figure 15. 10-W USB Charger Application Without Power Switch**



**Figure 16. 5-W USB Charger Application With Power Switch**



**Figure 17. 5-W USB Charger Application Without Power Switch**

## 7.4 Device Functional Modes

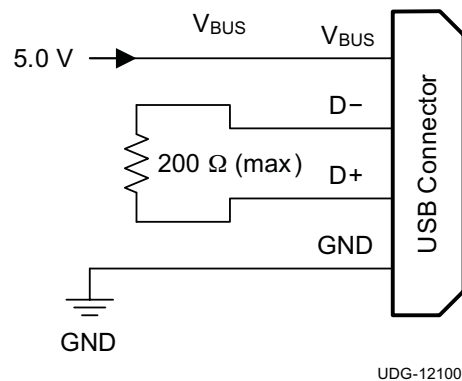
### 7.4.1 Dedicated Charging Port (DCP)

A dedicated charging port (DCP) is a downstream port on a device that outputs power through a USB connector, but is not capable of enumerating a downstream device, which generally allows portable devices to fast charge at their maximum rated current. A USB charger is a device with a DCP, such as a wall adapter or car power adapter. A DCP is identified by the electrical characteristics of its data lines. The following DCP identification circuits are usually used to meet the handshaking detections of different portable devices.

#### 7.4.1.1 Short the D+ Line to the D– Line

The USB BC1.2 Specification and the Chinese Telecommunications Industry Standard YD/T 1591-2009 define that the D+ and D– data lines must be shorted together with a maximum series impedance of 200  $\Omega$ . This is shown in [Figure 18](#).

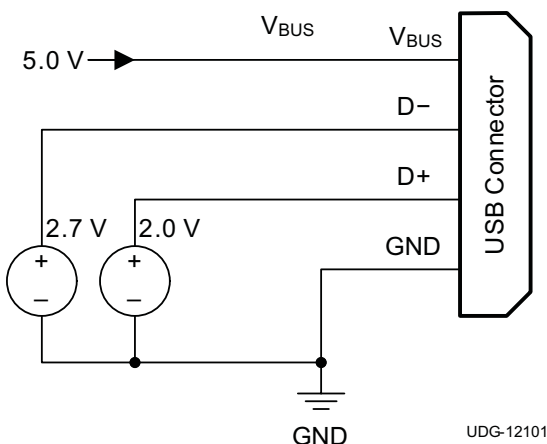
## Device Functional Modes (continued)



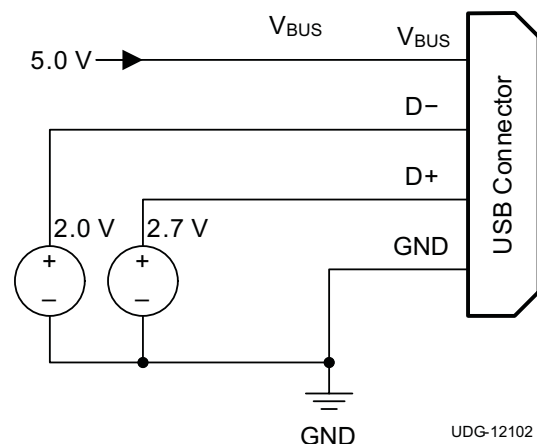
**Figure 18. DCP Short Mode**

### 7.4.1.2 Divider1 (DCP Applying 2 V on D+ Line and 2.7 V on D– Line) or Divider2 (DCP Applying 2.7 V on D+ Line and 2 V on D– Line)

There are two charging schemes for divider DCP. They are named after Divider1 and Divider2 DCPs that are shown in Figure 19 and Figure 20. The Divider1 charging scheme is used for 5-W adapters, Divider1 applies 2 V to the D+ line and 2.7 V to the D– data line. The Divider2 charging scheme is used for 10-W adapters and applies 2.7 V on the D+ line and 2 V is applied on the D– line.



**Figure 19. Divider1 DCP**



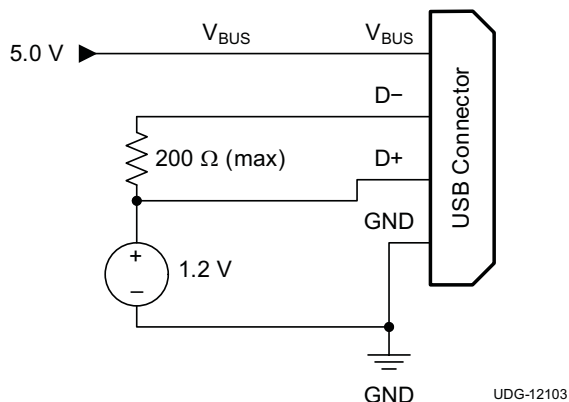
**Figure 20. Divider2 DCP**

### 7.4.1.3 Applying 1.2 V to the D+ Line and 1.2 V to the D– Line

As shown in Figure 21, some tablet USB chargers require 1.2 V on the shorted data lines of the USB connector. The maximum resistance between the D+ line and the D– line is 200 Ω.



## Device Functional Modes (continued)



**Figure 21. DCP Applying 1.2 V to the D+ Line and 1.2 V to the D- Line**

The TPS2511 is a combination of a current-limiting USB power switch and an USB DCP identification controller. Applications include vehicle power charger, wall adapters with USB DCP and other USB chargers. The TPS2511 DCP controller has the auto-detect feature that monitors the D+ and D- line voltages of the USB connector, providing the correct electrical characteristics on the DP and DM pins for the correct detections of compliant portable devices to fast charge. These portable devices include smart phones, 5-V tablets, and personal media players.

The TPS2511 power-distribution switch is intended for applications where heavy capacitive loads and short circuits are likely to be encountered, incorporating a 70-mΩ, N-channel MOSFET in a single package. This device provides hiccup mode when in current limit and OUT voltage is less than 3.8 V (typical) or an over-temperature protection occurs under an overload condition. Hiccup mode operation can reduce the output short-circuit current down to several milliamperes. The TPS2511 provides a logic-level enable EN pin to control the device turnon and turnoff and an open-drain output  $\overline{\text{CS}}$  for compensating  $V_{\text{BUS}}$  to account for cable  $I \times R$  voltage loss.

### 7.4.2 DCP Auto-Detect

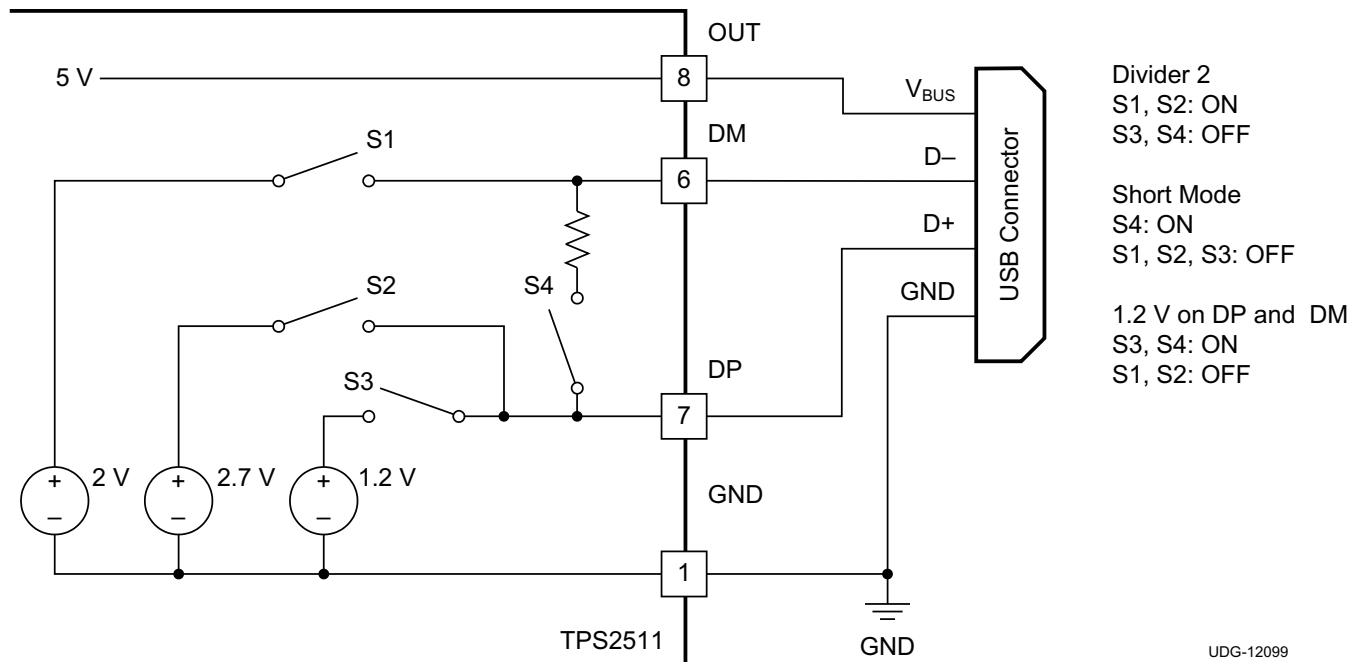
The TPS2511 integrates an *auto-detect* feature to support divider mode, short mode and 1.2 V / 1.2 V mode. If a divider device is attached, 2.7 V is applied to the DP pin and 2 V is applied to the DM pin. If a BC1.2-compliant device is attached, the TPS2511 automatically switches into short mode. If a device compliant with the 1.2 V / 1.2 V charging scheme is attached, 1.2 V is applied on both the DP pin and the DM pin. The functional diagram of DCP auto-detect feature is shown in [Figure 22](#).

## TPS2511

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[www.ti.com](http://www.ti.com)

### Device Functional Modes (continued)



**Figure 22. TPS2511 DCP Auto-Detect Functional Diagram**

## 8 Application and Implementation

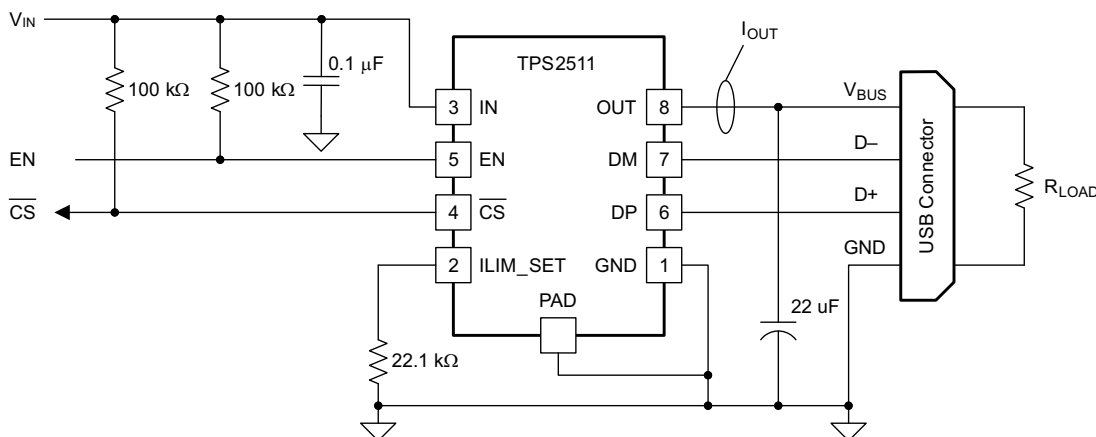
### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

The TPS2511 is a USB-dedicated charging-port controller and power switch with cable compensation. It is typically used for wall adapter or power bank as a USB charging controller and overcurrent protector.

### 8.2 Typical Application



**Figure 23. Test Circuit for System Operation**

#### 8.2.1 Design Requirements

For this design example, request IOS; Minimum must exceed 2100 mA.

When choosing the power switch, TI recommends following these general steps:

1. Determine the voltage of the power rail, 3.3 V or 5 V, and then choose the operation range of power switch can cove power rail.
2. Determine the normal operation current; for example, the maximum allowable current drawn by portable equipment for USB 2.0 port is 500 mA, so the normal operation current is 500 mA and the minimum current limit of power switch must exceed 500 mA to avoid false trigger during normal operation.
3. Determine the maximum allowable current provided by up-stream power, and then decide the maximum current limit of power switch that must lower it to ensure power switch can protect the up-stream power when overload is encountered at the output of power switch.

### NOTE

Choosing power switch with tighter current limit tolerance can loosen the up-stream power supply design.

#### 8.2.2 Detailed Design Procedure

The user-programmable  $R_{ILIM}$  resistor on the ILIMIT\_SET pin sets the current limit. The TPS2511 uses an internal regulation loop to provide a regulated voltage on the ILIM\_SET pin. The current limiting threshold is proportional to the current sourced out of the ILIM\_SET pin. The recommended 1% resistor range for  $R_{ILIM}$  is from 16.9 kΩ to 750 kΩ to ensure stability of the internal regulation loop, although not exceeding 210 kΩ results in a better accuracy. Many applications require that the minimum current limit remain above a certain current

## Typical Application (continued)

level or that the maximum current limit remain below a certain current level, so it is important to consider the tolerance of the overcurrent threshold when selecting a value for  $R_{ILIM}$ . Equation 6 and Equation 7 calculate the resulting overcurrent thresholds for a given external resistor value ( $R_{ILIM}$ ). The traces routing the  $R_{ILIM}$  resistor to the TPS2511 must be as short as possible to reduce parasitic effects on the current limit accuracy. The equations along with Figure 24 and Figure 25 can be used to estimate the minimum and maximum variation of the current limit threshold for a predefined resistor value. This variation disregards the inaccuracy of the resistor itself.

$$I_{OS\_MIN} = \frac{51228}{R_{ILIM}^{1.030}}$$

where

- $I_{OS\_MIN}$  is in mA
- $R_{ILIM}$  is in  $k\Omega$

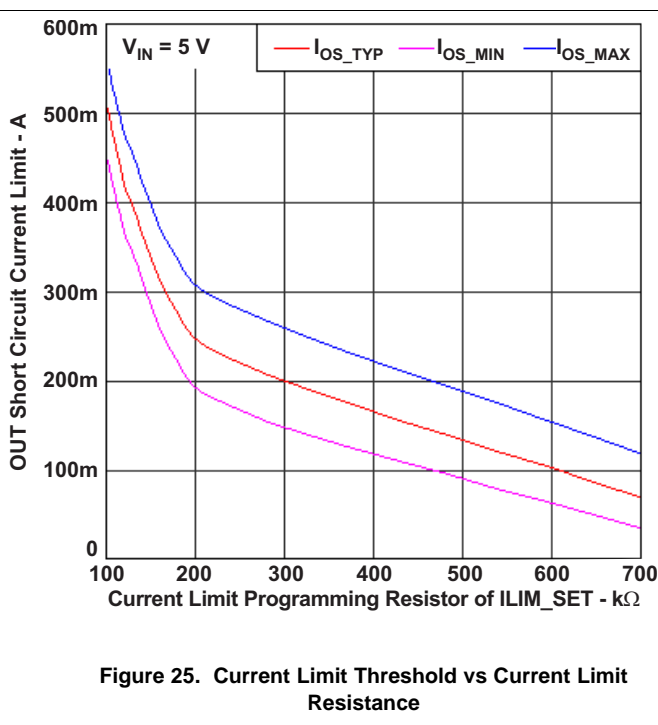
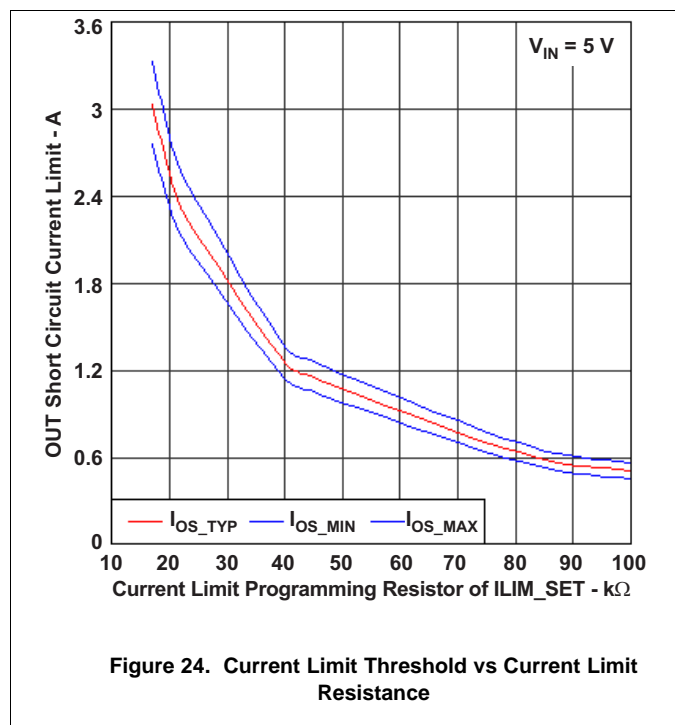
(6)

$$I_{OS\_MAX} = \frac{51228}{R_{ILIM}^{0.967}}$$

where

- $I_{OS\_MAX}$  is in mA
- $R_{ILIM}$  is in  $k\Omega$

(7)



For this example design, as shown in Equation 8,  $I_{OS\_MIN} = 2100$  mA.

$$I_{OS\_MIN} = \frac{51228}{R_{ILIM}^{1.03}} = 2100 \text{ mA}$$

(8)

$$R_{ILIM} = \left( \frac{51228}{I_{OS\_MIN}} \right)^{\frac{1}{1.03}} = \left( \frac{51228}{2100} \right)^{\frac{1}{1.03}} = 22.227 \text{ k}\Omega$$

(9)

## Typical Application (continued)

Including resistor tolerance, target nominal resistance value given by [Equation 10](#).

$$R_{ILIM} = \frac{22.227 \text{ k}\Omega}{1.01 \text{ k}\Omega} = 22.007 \text{ k}\Omega \quad (10)$$

Choose [Equation 11](#).

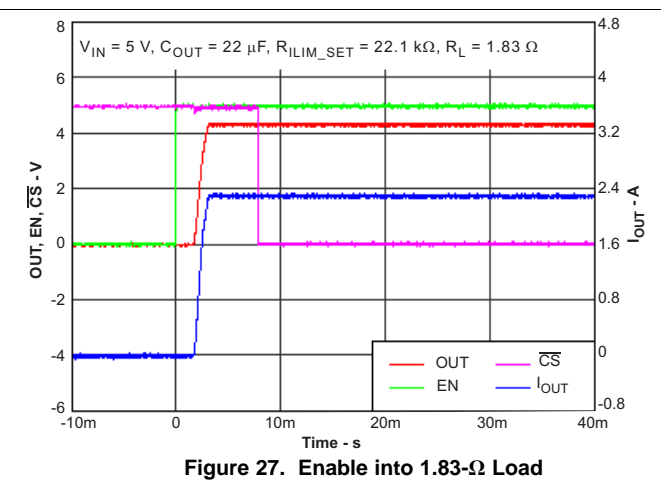
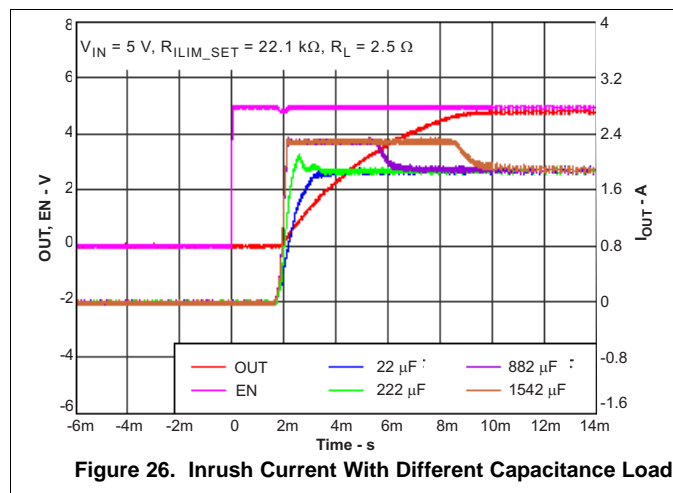
$$R_{ILIM} = 22 \text{ k}\Omega \quad (11)$$

### 8.2.2.1 Input and Output Capacitance

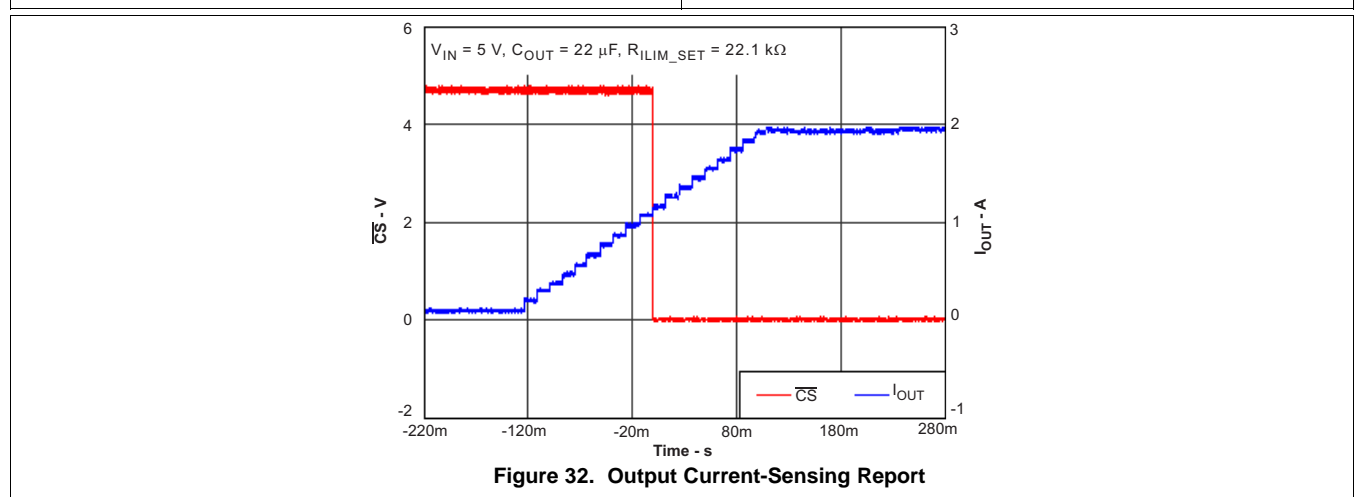
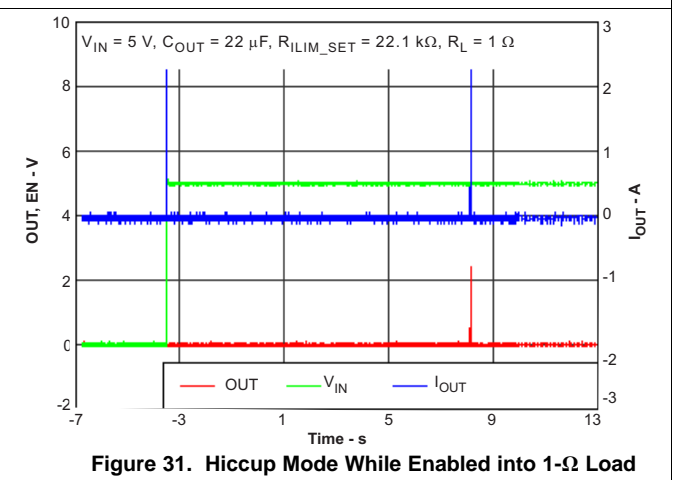
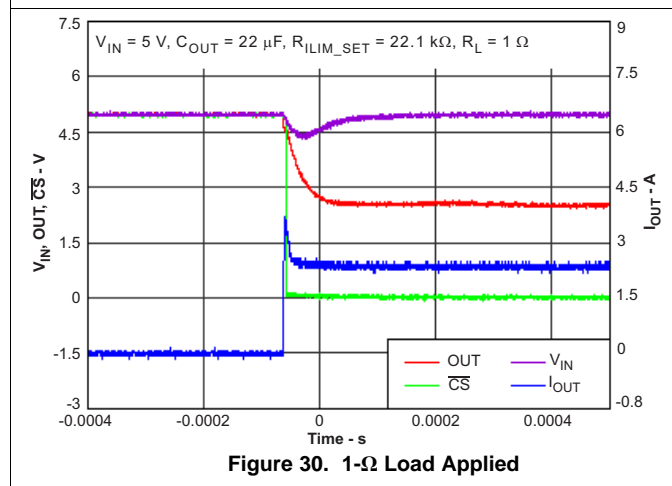
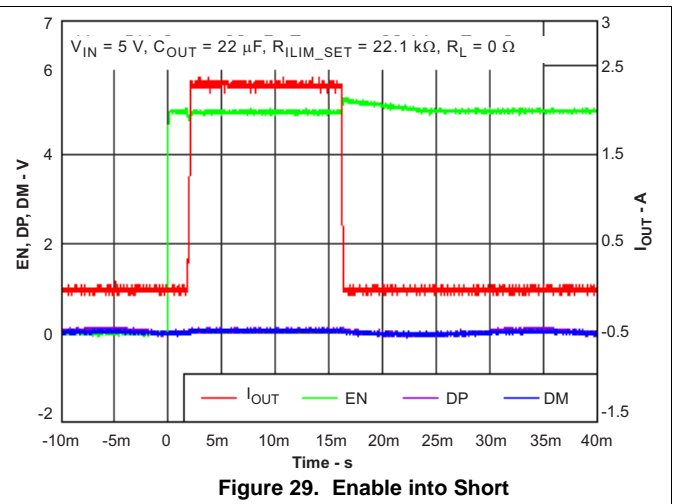
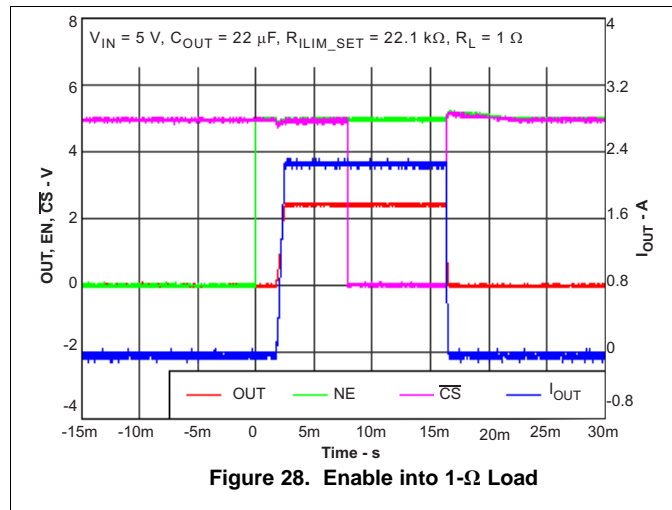
Input and output capacitance improves the performance of the device; the actual capacitance must be optimized for the particular application. For all applications, TI recommends placing a 0.1-μF or greater ceramic bypass capacitor between IN and GND, as close to the device as possible for local noise decoupling. This precaution reduces ringing on the input due to power-supply transients. Additional input capacitance may be needed on the input to reduce voltage undershoot from exceeding the UVLO of other load share one power rail with TPS2511 or overshoot from exceeding the absolute-maximum voltage of the device during heavy transient conditions. This is especially important during bench testing when long, inductive cables are used to connect the evaluation board to the bench power supply.

TI recommends placing at least a 22-μF ceramic capacitor or higher-value electrolytic capacitor on the output pin when large transient currents are expected on the output to reduce the undershoot, which is caused by the inductance of the output power bus just after a short has occurred and the TPS2511 has abruptly reduced OUT current. Energy stored in the inductance drives the OUT voltage down and potentially negative as it discharges.

### 8.2.3 Application Curves



## Typical Application (continued)



## 9 Power Supply Recommendations

Design of the devices is for operation from an input voltage supply range of 4.5 V to 5.5 V. The current capability of the power supply must exceed the maximum current limit of the power switch.



## 11 Device and Documentation Support

### 11.1 Documentation Support

#### 11.1.1 Related Documentation

For related documentation see the following:

[Effective System ESD Protection Guidelines:TPS251x USB Charging Port Controllers](#) (SLVA800)

### 11.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 11.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 11.4 Trademarks

PowerPAD, E2E are trademarks of Texas Instruments.  
All other trademarks are the property of their respective owners.

### 11.5 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 11.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TPS2511DGN</a>	Active	Production	HVSSOP (DGN)   8	80   TUBE	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	2511
TPS2511DGN.A	Active	Production	HVSSOP (DGN)   8	80   TUBE	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	2511
<a href="#">TPS2511DGNR</a>	Active	Production	HVSSOP (DGN)   8	2500   LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	2511
TPS2511DGNR.A	Active	Production	HVSSOP (DGN)   8	2500   LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	2511

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**OTHER QUALIFIED VERSIONS OF TPS2511 :**

- Automotive : [TPS2511-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS2511DGNR	HVSSOP	DGN	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

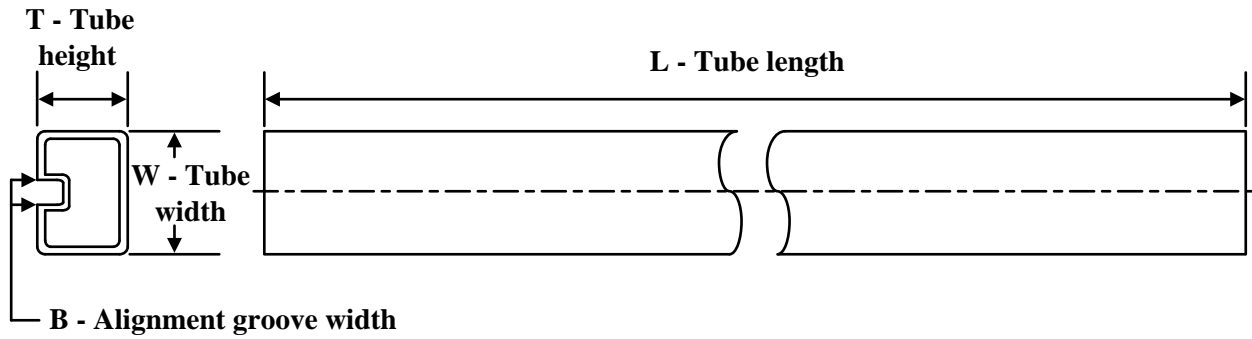
## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS2511DGNR	HVSSOP	DGN	8	2500	366.0	364.0	50.0

## TUBE



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TPS2511DGN	DGN	HVSSOP	8	80	330	6.55	500	2.88
TPS2511DGN.A	DGN	HVSSOP	8	80	330	6.55	500	2.88

## GENERIC PACKAGE VIEW

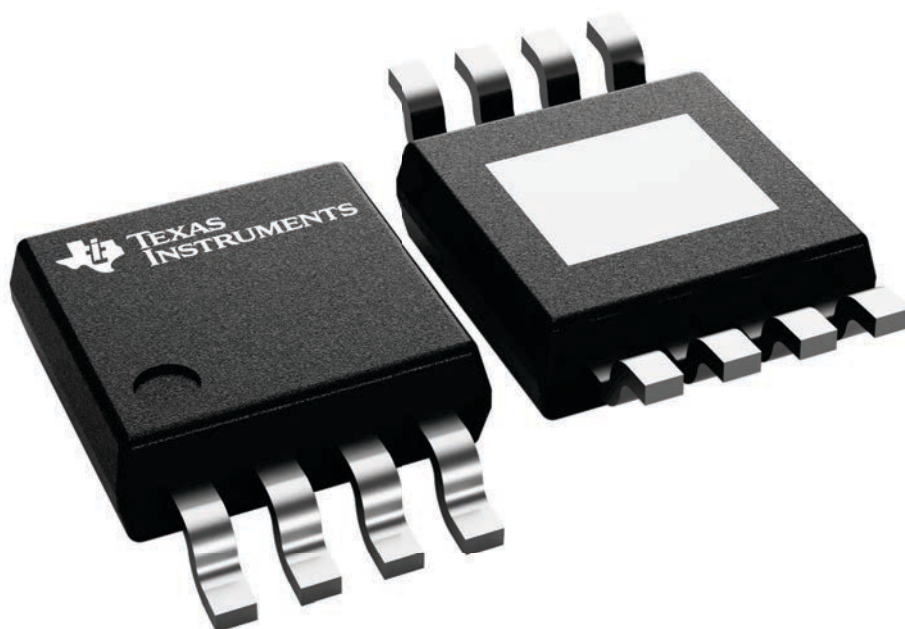
**DGN 8**

**PowerPAD™ HVSSOP - 1.1 mm max height**

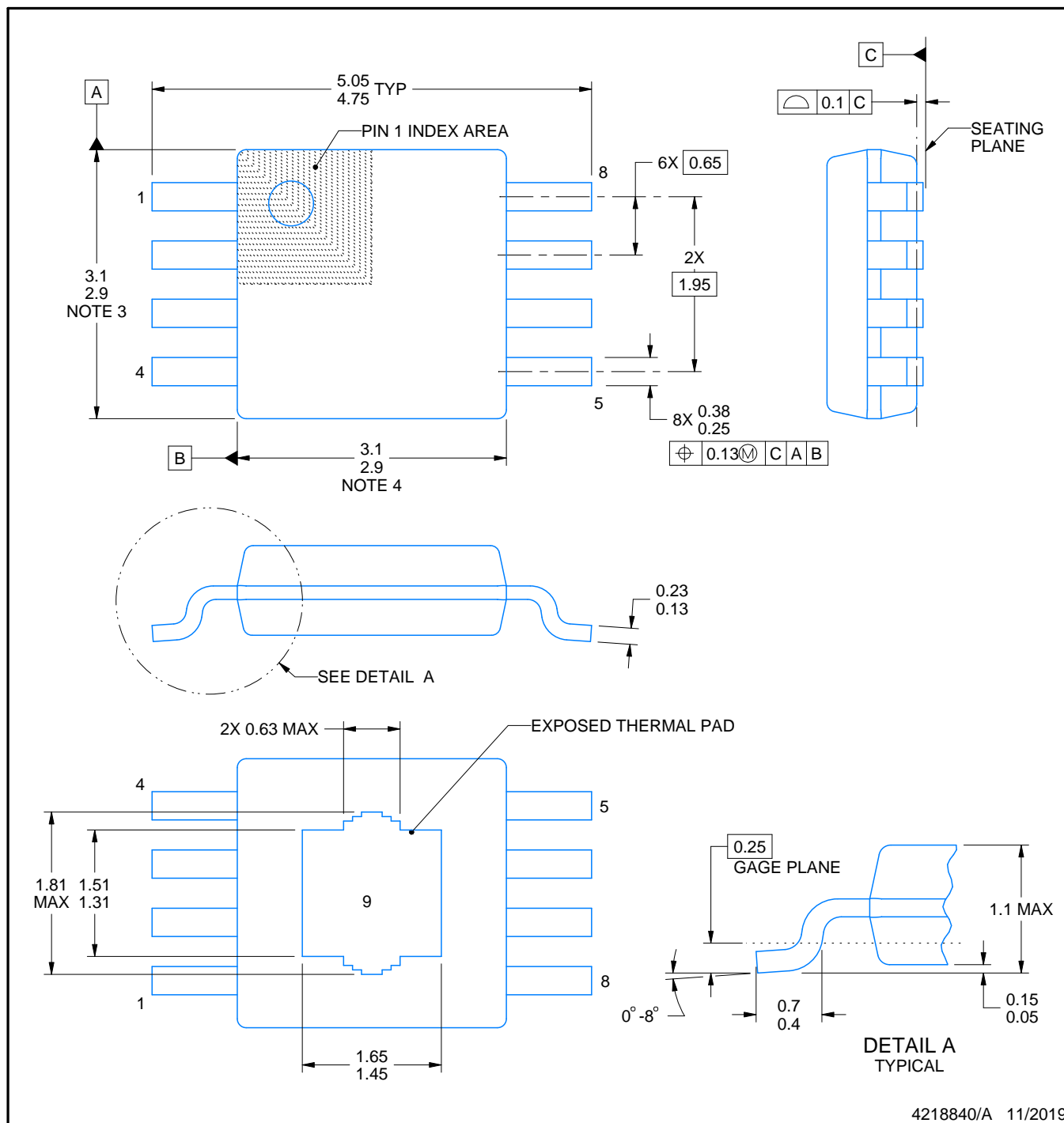
**3 x 3, 0.65 mm pitch**

SMALL OUTLINE PACKAGE

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



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4218840/A 11/2019

## NOTES:

PowerPAD is a trademark of Texas Instruments.

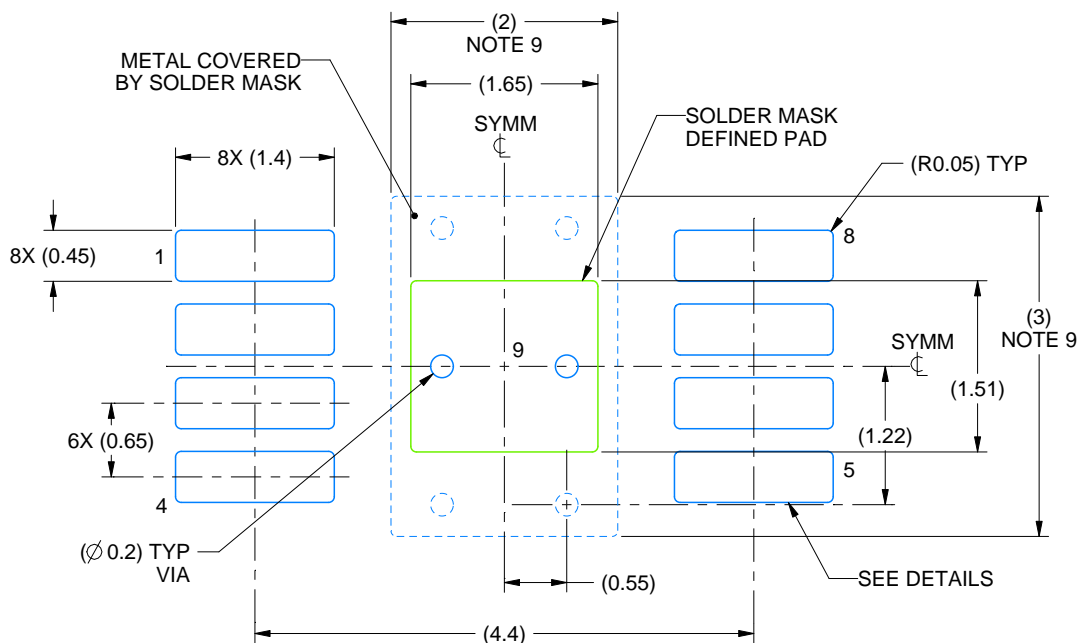
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.

# EXAMPLE BOARD LAYOUT

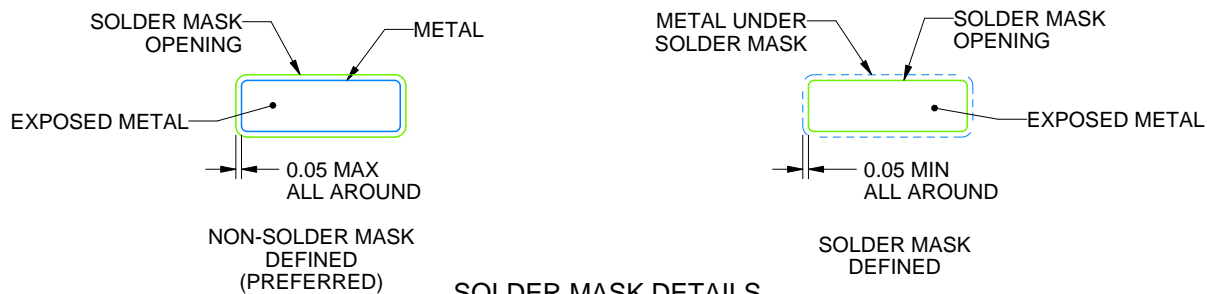
DGN0008E

PowerPAD VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 15X



SOLDER MASK DETAILS

4218840/A 11/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.

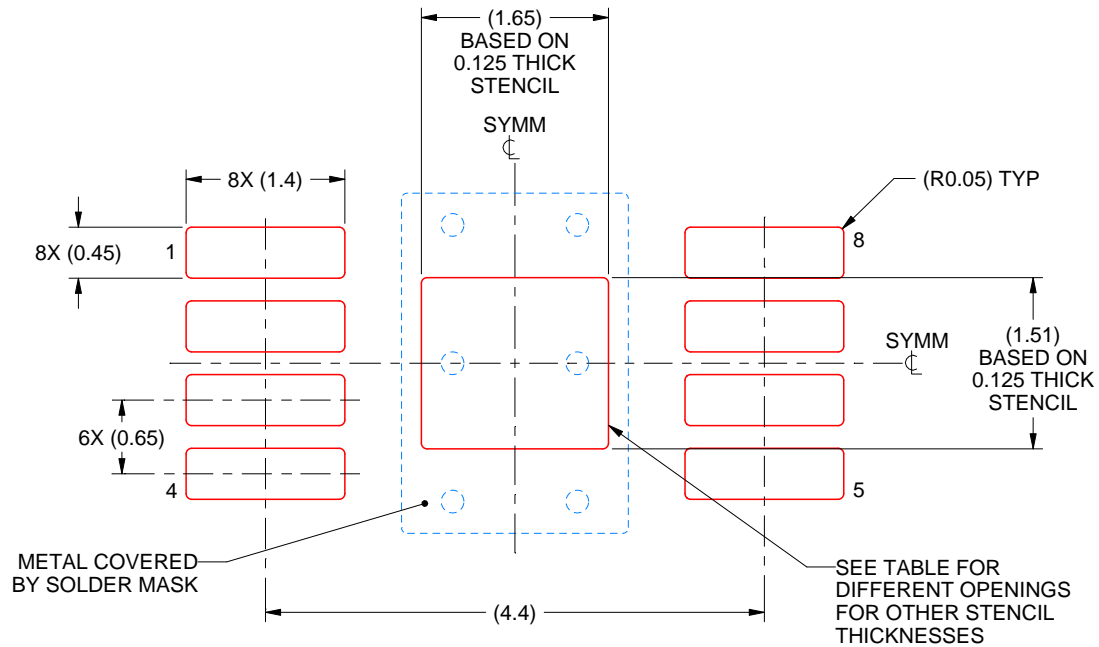


# EXAMPLE STENCIL DESIGN

DGN0008E

PowerPAD VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



**SOLDER PASTE EXAMPLE**  
EXPOSED PAD 9:  
100% PRINTED SOLDER COVERAGE BY AREA  
SCALE: 15X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	1.84 X 1.69
0.125	1.65 X 1.51 (SHOWN)
0.15	1.51 X 1.38
0.175	1.39 X 1.28

4218840/A 11/2019

NOTES: (continued)

10. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
11. Board assembly site may have different recommendations for stencil design.

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